

Notice of References Cited	Application/Control No. 10/024,957	Applicant(s)/Patent Under Reexamination MALUF ET AL.	
	Examiner Robert A. Siconolfi	Art Unit 3683	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5,400,824	03-1995	Gschwendtner et al.	137/625.28
	B	US-5,909,078	06-1999	Wood et al.	310/307
	C	US-6,019,437	02-2000	Barron et al.	303/113.1
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Klaassen et al, "Silicon Fusion Bonding and DeepReactive Ion Etching; A New Technology For Microstructures" Proc.Transducers 95 Stockholm Sweden pp.556-559
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.